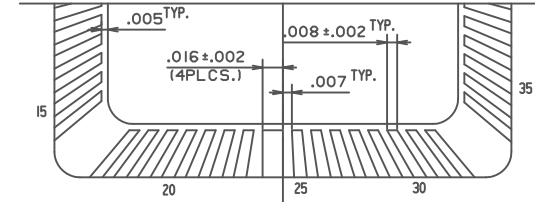
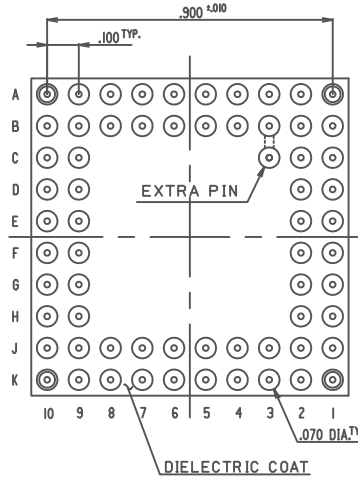
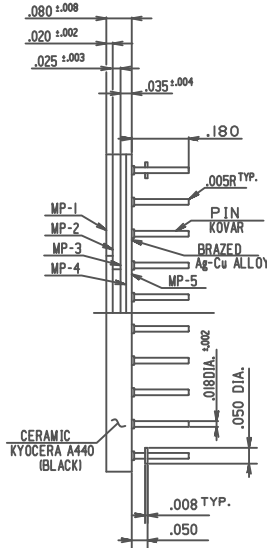
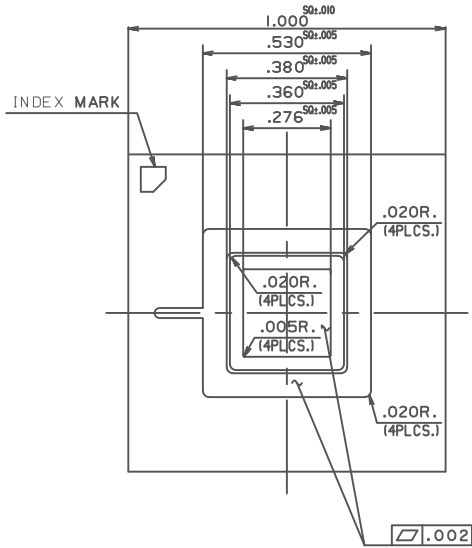


SSM P/N CPG06420

REVISIONS			
REV.	DESCRIPTION	DATE	APPROVAL



WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	A1	21	J4	41	E10	61	A3
2	C2	22	K4	42	E9	62	B3
3	B1	23	K5	43	D10	63	A2
4	C1	24	J5	44	D9	64	B2
5	D2	25	K6	45	C10		
6	D1	26	J6	46	C9		
7	E1	27	K7	47	B10		
8	E2	28	J7	48	B9		
9	F1	29	K8	49	A10		
10	F2	30	J8	50	B8		
11	G1	31	K9	51	A9		
12	G2	32	J9	52	A8		
13	H1	33	K10	53	B7		
14	H2	34	H9	54	A7		
15	J1	35	J10	55	A6		
16	J2	36	H10	56	B6		
17	K1	37	G9	57	A5		
18	J3	38	G10	58	B5		
19	K2	39	F10	59	A4		
20	K3	40	F9	60	B4		

S/R	NC
D/A	NC
EXTRA PIN (C3)	B3

NOTES:

1. PLATING THICKNESS TO BE 60 MICRO INCHES GOLD OVER 100 MICRO INCHES MINIMUM NICKEL, UNLESS OTHERWISE STATED IN P.I.
2. SEAL RING TO BE METALLIZED.
3. DIE ATTACH TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 800m Ω MAX.
6. EQUIVALENT TO KYOCERA DWG. NO. KD-P91198-A

Qty Req'd	Part or Identifying No.	Code Ident	Description	Material or Note	Specification or Reference Desig	Item No.
List of Materials or Parts List						
			Drawn	Date		
			Check	Date		
Next Assy	Qty		Approved	Date		
Controlling Units (millimeters inches)			Approved	Date		
W=±.1			Approved	Date	Code Ident	
D=±.02					Size	
R=±.002					D	
T=±.002					Drawing No.	6300470
Angle=±.2°					Rev	NC
			Approved	Date	Scale	5:1
					CAD File No=	p470PK0
						Sheet 1 of 1



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